

# VTX

对New baseline 的结构方案讨论  
(基于当前完成的VTX两种局部支撑结构+风道放大腔的整体模型)

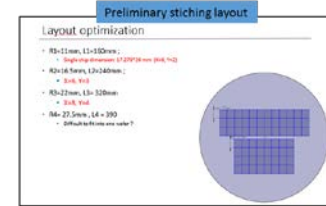
- 走线空间受限
- Sticking结构线路引出和探测器支撑与固定

VTX structure - stitching technology based

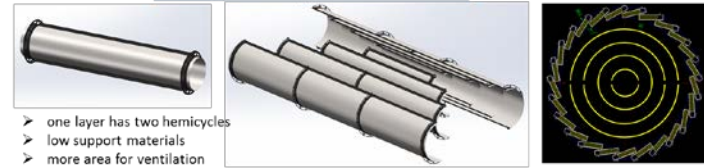
## ■ 4 single layer of bent MAPS structure

Many mechanical related issues being discussed and to be studied:

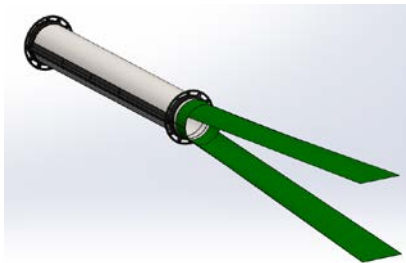
- Wafer thickness VS bent radius
- Wire bond and cable routing?
- shape retaining and connection in Z direction
- Ventilation of air cooling
- Layers integration on the beam



Preliminary structure design of the bent MAPS detector



VTX+风道放大腔总体结构模型



# OTK

重点对物理上优先考虑的热沉方案，初步进行了模拟热分析，初始尺寸方案已有结果：

对比外侧搭桥方案，同样应用铜材料，显示热沉效果比较好。

后按更新的发热量，调整热沉材料为AL，同样管数量下效果也比较好。

ASIC Power: 28.14W (15x140x3 mm)  
 PCB t=1.6mm  
 LGAD t= 0.5mm  
 冷管温度5°C

